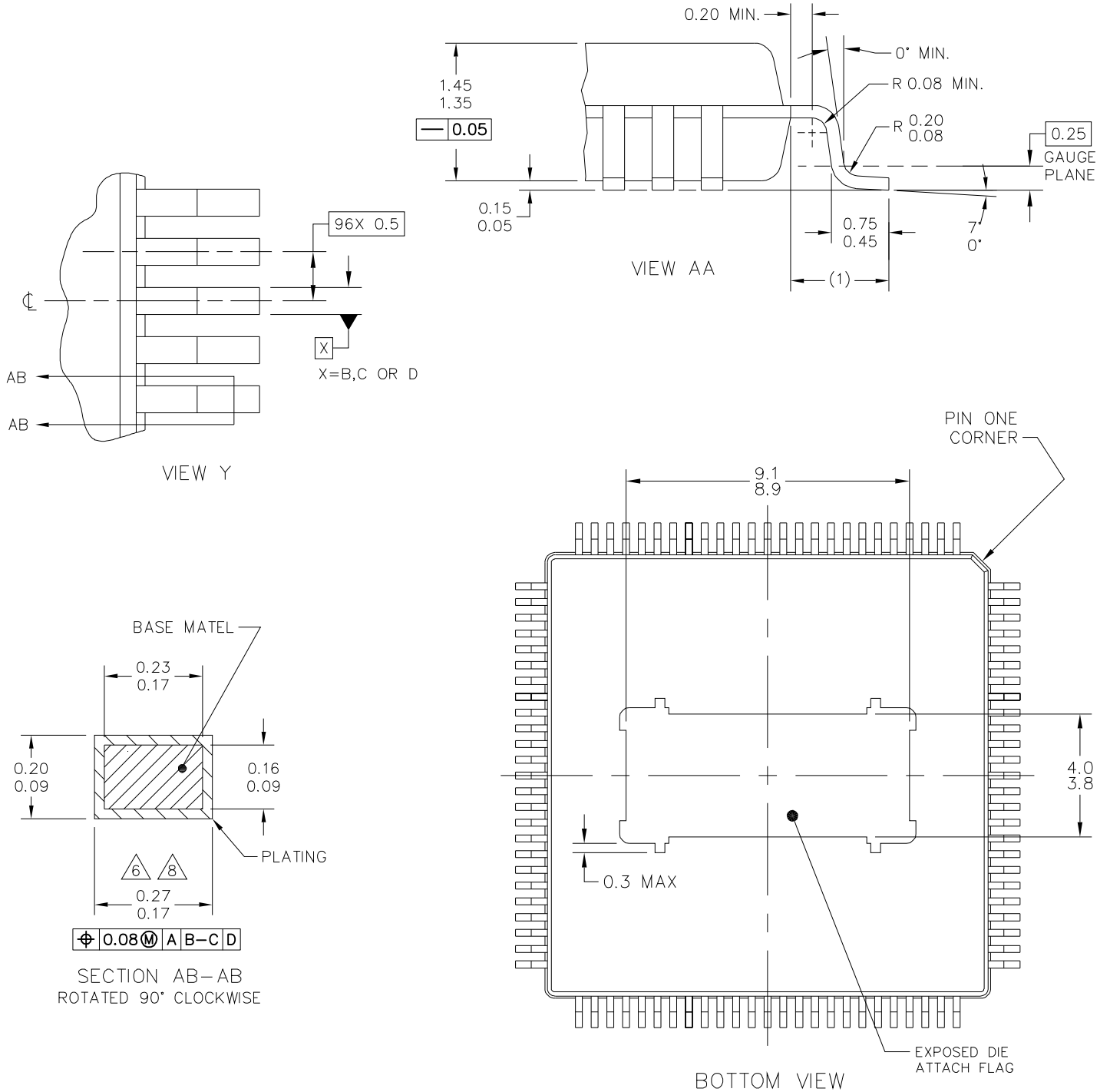


RELEASED FOR EXTERNAL ASSEMBLY ONLY
 THIS DESIGN ONLY MEETS EXTERNAL DESIGN AND ASSEMBLY RULES. MUST BE REVIEWED
 AND UPDATED BEFORE BEING ASSEMBLED INTERNALLY.

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NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1994.
2. DIMENSIONS IN MILLIMETERS.
3. DATUMS B-C AND D TO BE DETERMINED AT DATUM PLANE H.

4. THESE DIMENSIONS TO BE DETERMINED AT SEATING PLANE, DATUM A.

5. THESE DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.25 PER SIDE. THESE DIMENSIONS DO INCLUDE MOLD MISMATCH. THESE DIMENSIONS ARE TO BE DETERMINED AT DATUM PLANE H..

6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.35. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07.

7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10MM AND 0.25MM FROM THE LEAD TIP.

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